

Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Average Rectified Output Current	l ₀	2.0	Α
Repetitive Peak Forward Current (Pulse Wave = 1 Sec, Duty Cycle = 66%)	I _{FRM}	4.2	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	20	А

Thermal Characteristics

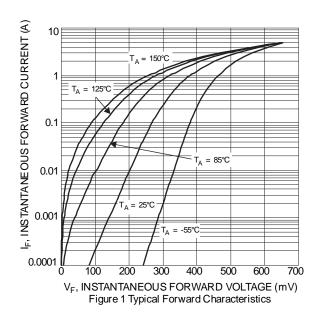
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	155	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

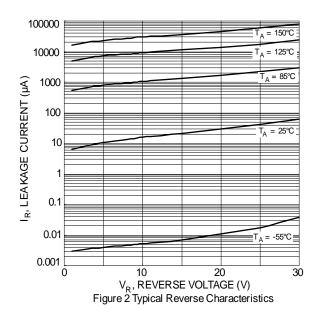
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	VF	-	0.38	0.42	V	I _F = 1.0A
		_	0.45	0.48		I _F = 2.0A
Reverse Current (Note 6)	I _R	_	_	150	μA	V _R = 30V
Junction Capacitance	CJ	1	110	1	pF	$V_R = 4V, f = 1.0MHz$

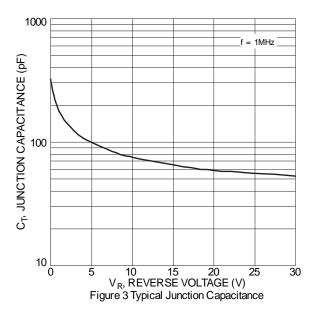
Notes:

- 5. Device mounted on FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
- 6. Short duration pulse test used to minimize self-heating effect.



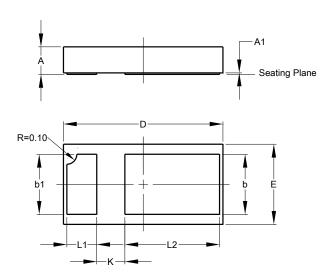






Package Outline Dimensions (Note 7)

Please see http://www.diodes.com/package-outlines.html for the latest version.

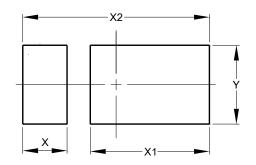


X3-WLB1608-2				
Dim	Min	Max	Тур	
Α	0.250	0.300	0.275	
A 1	-	0.015	-	
b	-	-	0.600	
b1	-	-	0.600	
D	1.57	1.63	1.60	
Е	0.77	0.83	0.80	
K	-	-	0.282	
L1	0.25	0.35	0.30	
L2	0.90	1.00	0.95	
All Dimensions in mm				

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
X	0.385
X1	1.035
X2	1.622
Υ	0.690



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